



**BSI Standards Publication**

# **Semiconductor devices — Mechanical and climatic test methods**

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Part 22-2: Bond strength — Wire bond shear test methods

## National foreword

This British Standard is the UK implementation of EN IEC 60749-22-2:2026. It is identical to IEC 60749-22-2:2025. Together with BS EN IEC 60749-22-1:2026, it partially supersedes BS EN 60749-22:2003, which will be withdrawn on 31 January 2029.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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### Amendments/corrigenda issued since publication

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